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September 2011

Features

- Internal control latches and address decoder
- Short set-up and hold times
- Wide operating voltage: 4.5 V to 13.2 V
- 12 V_{pp} analog signal capability
- R_{ON} 65 Ω max. @ V_{DD} = 12 V, 25°C
- ΔR_{ON} ≤ 10 Ω @ V_{DD} = 12 V, 25°C
- Full CMOS switch for low distortion
- Minimum feedthrough and crosstalk
- Separate analog and digital reference supplies
- Low power consumption ISO-CMOS technology

Applications

- Key systems
- PBX systems
- Mobile radio
- Test equipment /instrumentation
- Analog/digital multiplexers
- Audio/Video switching

Ordering Information

MT8808AP1	28 Pin PLCC*	Tubes
MT8808APR1	28 Pin PLCC*	Tape & Reel
MT8808AE1	28 Pin PDIP*	Tubes

* Pb Free Matte Tin
 -40°C to +85°C

Description

The Zarlink MT8808 is fabricated in Zarlink's ISO-CMOS technology providing low power dissipation and high reliability. The device contains a 8 x 8 array of crosspoint switches along with a 6 to 64 line decoder and latch circuits. Any one of the 64 switches can be addressed by selecting the appropriate six address bits. The selected switch can be turned on or off by applying a logical one or zero to the DATA input. V_{SS} is the ground reference of the digital inputs. The range of the analog signal is from V_{DD} to V_{EE}.

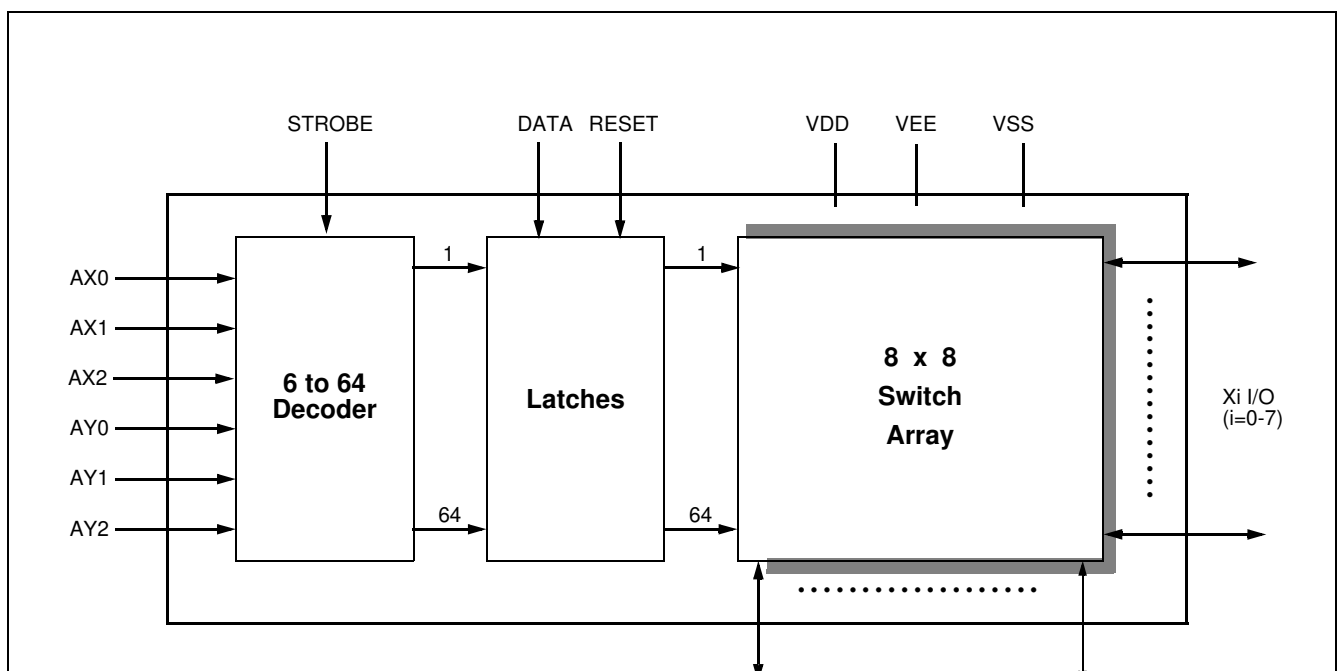


Figure 1 - Functional Block Diagram

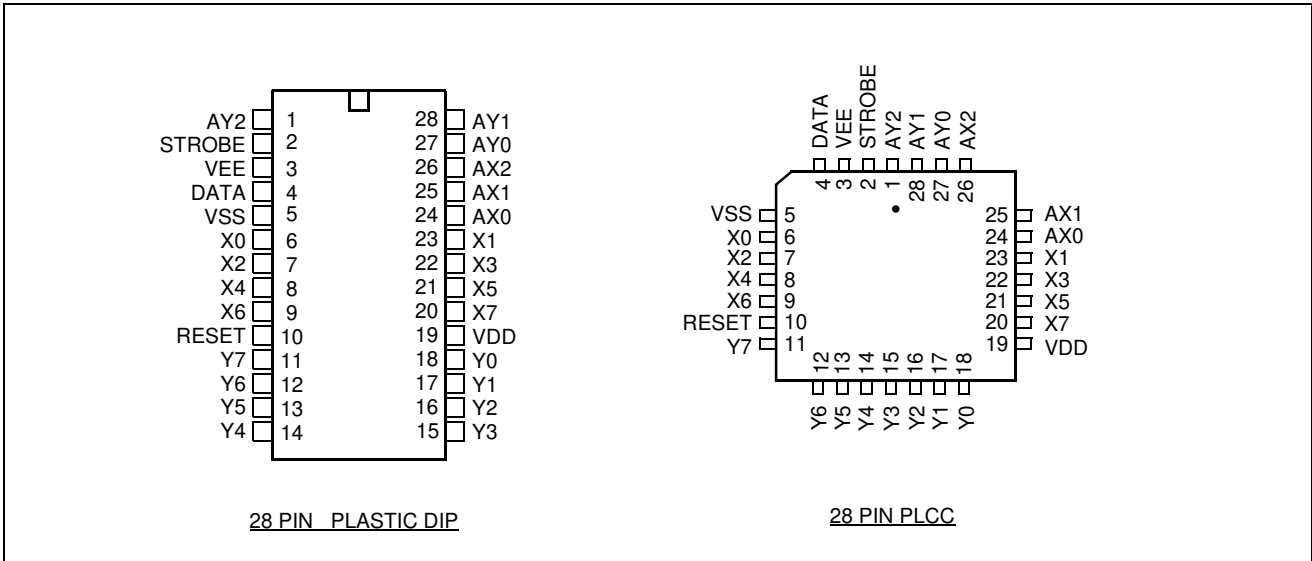


Figure 2 - Pin Connections

Change Summary

Changes from the May 2005 issue to the September 2011 issue.

Page	Item	Change
1	Ordering Information	Removed leaded packages as per PCN notice.

Pin Description

Pin #	Name	Description
1	AY2	AY2 Address Line (Input).
2	STROBE	STROBE (Input): enables function selected by address and data. Address must be stable before STROBE goes high and DATA must be stable on the falling edge of the STROBE. Active High.
3	V _{EE}	Negative Power Supply.
4	DATA	DATA (Input): a logic high input will turn on the selected switch and a logic low will turn off the selected switch. Active High.
5	V _{SS}	Digital Ground Reference.
6-9	X0, X2, X4, X6	X0, X2, X4 and X6 Analog (Inputs/Outputs): these are connected to the X0, X2, X4 and X6 rows of the switch array.
10	RESET	Master RESET (Input): this is used to turn off all switches. Active High.
11-18	Y7 - Y0	Y7 - Y0 Analog (Inputs/Outputs): these are connected to the Y0 - Y7 columns of the switch array.
19	V _{DD}	Positive Power Supply.

Pin Description

Pin #	Name	Description
20-23	X7, X5, X3, X1	X7, X5, X3 and X1 Analog (Inputs/Outputs): these are connected to the X7, X5, X3 and X1 rows of the switch array.
24-26	AX0-AX2	AX0 - AX2 Address Lines (Inputs).
27,28	AY0, AY1	AY0 and AY1 Address Lines (Inputs).

Functional Description

The MT8808 is an analog switch matrix with an array size of 8 x 8. The switch array is arranged such that there are 8 columns by 8 rows. The columns are referred to as the Y inputs/outputs and the rows are the X inputs/outputs. The crosspoint analog switch array will interconnect any X I/O with any Y I/O when turned on and provide a high degree of isolation when turned off. The control memory consists of a 64 bit write only RAM in which the bits are selected by the address inputs (AY0-AY2, AX0-AX2). Data is presented to the memory on the DATA input. Data is asynchronously written into memory whenever the STROBE input is high and is latched on the falling edge of STROBE. A logical "1" written into a memory cell turns the corresponding crosspoint switch on and a logical "0" turns the crosspoint off. Only the crosspoint switches corresponding to the addressed memory location are altered when data is written into memory. The remaining switches retain their previous states. Any combination of X and Y inputs/outputs can be interconnected by establishing appropriate patterns in the control memory. A logical "1" on the RESET input will asynchronously return all memory locations to logical "0" turning off all crosspoint switches. Two voltage reference pins (V_{SS} and V_{EE}) are provided for the MT8808 to enable switching of negative analog signals. The range for digital signals is from V_{DD} to V_{SS} while the range for analog signals is from V_{DD} to V_{EE} . V_{SS} and V_{EE} pins can be tied together if a single voltage reference is needed.

Address Decode

The six address inputs along with the STROBE are logically ANDed to form an enable signal for the resettable transparent latches. The DATA input is buffered and is used as the input to all latches. To write to a location, RESET must be low while the address and data are set up. Then the STROBE input is set high and then low causing the data to be latched. The data can be changed while STROBE is high, however, the corresponding switch will turn on and off in accordance with the DATA input. DATA must be stable on the falling edge of STROBE in order for correct data to be written to the latch.

Absolute Maximum Ratings* - Voltages are with respect to V_{EE} unless otherwise stated.

	Parameter	Symbol	Min.	Max.	Units
1	Supply Voltage	V_{DD}	-0.3	15.0	V
		V_{SS}	-0.3	$V_{DD}+0.3$	V
2	Analog Input Voltage	V_{INA}	-0.3	$V_{DD}+0.3$	V
3	Digital Input Voltage	V_{IN}	$V_{SS}-0.3$	$V_{DD}+0.3$	V
4	Current on any I/O Pin	I		± 15	mA
5	Storage Temperature	T_S	-65	+150	$^{\circ}\text{C}$
6	Package Power Dissipation PLASTIC DIP	P_D		0.6	W

* Exceeding these values may cause permanent damage. Functional operation under these conditions is not implied.

Recommended Operating Conditions - Voltages are with respect to V_{EE} unless otherwise stated.

	Characteristics	Sym.	Min.	Typ.	Max.	Units	Test Conditions
1	Operating Temperature	T_O	-40	25	85	$^{\circ}\text{C}$	
2	Supply Voltage	V_{DD}	4.5		13.2	V	
		V_{SS}	V_{EE}		$V_{DD}-4.5$	V	
3	Analog Input Voltage	V_{INA}	V_{EE}		V_{DD}	V	
4	Digital Input Voltage	V_{IN}	V_{SS}		V_{DD}	V	

DC Electrical Characteristics[†] - Voltages are with respect to $V_{EE} = V_{SS} = 0\text{ V}$, $V_{DD} = 12\text{ V}$ unless otherwise stated.

	Characteristics	Sym.	Min.	Typ. [‡]	Max.	Units	Test Conditions
1	Quiescent Supply Current	I_{DD}		1	100	μA	All digital inputs at $V_{IN} = V_{SS}$ or V_{DD}
				0.4	1.5	mA	All digital inputs at $V_{IN} = 2.4 + V_{SS}$; $V_{SS} = 7.0\text{ V}$
				5	15	mA	All digital inputs at $V_{IN} = 3.4\text{ V}$
2	Off-state Leakage Current (See G.9 in Appendix)	I_{OFF}		± 1	± 500	nA	$ V_{X_i} - V_{Y_j} = V_{DD} - V_{EE}$ See Appendix, Fig. A.1
3	Input Logic "0" level	V_{IL}			$0.8+V_s$	V	$V_{SS} = 7.5\text{ V}$; $V_{EE} = 0\text{ V}$
4	Input Logic "1" level	V_{IH}	$2.0+V_{SS}$			V	$V_{SS} = 6.5\text{ V}$; $V_{EE} = 0\text{ V}$
5	Input Logic "1" level	V_{IH}	3.3			V	
6	Input Leakage (digital pins)	I_{LEAK}		0.1	10	μA	All digital inputs at $V_{IN} = V_{SS}$ or V_{DD}

[†] DC Electrical Characteristics are over recommended temperature range.

[‡] Typical figures are at 25°C and are for design aid only; not guaranteed and not subject to production testing.

DC Electrical Characteristics- Switch Resistance - V_{DC} is the external DC offset applied at the analog I/O pins.

	Characteristics	Sym.	25°C		70°C		85°C		Units	Test Conditions
			Typ.	Max.	Typ.	Max.	Typ.	Max.		
1	On-state Resistance $V_{DD} = 12\text{ V}$ $V_{DD} = 10\text{ V}$ $V_{DD} = 5\text{ V}$ (See G.1, G.2, G.3 in Appendix)	R_{ON}	45	65		75		80	Ω	$V_{SS}=V_{EE} = 0\text{ V}, V_{DC} = V_{DD}/2,$ $ V_{Xi}-V_{Yj} = 0.4\text{ V}$ See Appendix, Fig. A.2
			55	75		85		90	Ω	
			120	185		215		225	Ω	
2	Difference in on-state resistance between two switches (See G.4 in Appendix)	ΔR_{ON}	5	10		10		10	Ω	$V_{DD}=12\text{V}, V_{SS}=V_{EE}=0,$ $V_{DC}=V_{DD}/2,$ $ V_{Xi}-V_{Yj} = 0.4\text{V}$ See Appendix, Fig. A.2

AC Electrical Characteristics[†] - Crosspoint Performance- Voltages are with respect to $V_{DD}=5\text{V}$, $V_{SS}=0\text{V}$, $V_{EE}=-7\text{V}$, unless otherwise stated.

	Characteristics	Sym.	Min.	Typ. [‡]	Max.	Units	Test Conditions
1	Switch I/O Capacitance	C_S		20		pF	$f = 1\text{ MHz}$
2	Feedthrough Capacitance	C_F		0.2		pF	$f = 1\text{ MHz}$
3	Frequency Response Channel "ON" $20\text{LOG}(V_{OUT}/V_{Xi})=-3\text{ dB}$	F_{3dB}		45		MHz	Switch is "ON"; $V_{INA} = 2\text{ Vpp}$ sinewave; $R_L = 1\text{ k}\Omega$ See Appendix, Fig. A.3
4	Total Harmonic Distortion (See G.5, G.6 in Appendix)	THD		0.01		%	Switch is "ON"; $V_{INA} = 2\text{ Vpp}$ sinewave $f = 1\text{ kHz}$; $R_L=1\text{ k}\Omega$
5	Feedthrough Channel "OFF" Feed.= $20\text{LOG}(V_{OUT}/V_{Xi})$ (See G.8 in Appendix)	FDT		-95		dB	All Switches "OFF"; $V_{INA}=2\text{Vpp}$ sinewave $f = 1\text{ kHz}$; $R_L = 1\text{ k}\Omega$. See Appendix, Fig. A.4
6	Crosstalk between any two channels for switches X_i-Y_i and X_j-Y_j . $X_{talk}=20\text{LOG}(V_{Yj}/V_{Xi})$. (See G.7 in Appendix).	X_{talk}		-45		dB	$V_{INA} = 2\text{ Vpp}$ sinewave $f = 10\text{ MHz}$; $R_L = 75\ \Omega$.
				-90		dB	$V_{INA} = 2\text{ Vpp}$ sinewave $f = 10\text{ kHz}$; $R_L = 600\ \Omega$.
				-85		dB	$V_{INA} = 2\text{ Vpp}$ sinewave $f = 10\text{ kHz}$; $R_L = 1\text{ k}\Omega$.
				-80		dB	$V_{INA}=2\text{Vpp}$ sinewave $f = 1\text{ kHz}$; $R_L = 10\text{ k}\Omega$. Refer to Appendix, Fig. A.5 for test circuit.
7	Propagation delay through switch	t_{PS}			30	ns	$R_L = 1\text{ k}\Omega$; $C_L = 50\text{ pF}$

[†] Timing is over recommended temperature range. See Fig. 3 for control and I/O timing details.

[‡] Typical figures are at 25°C and are for design aid only; not guaranteed and not subject to production testing.

Crosstalk measurements are for Plastic DIPS only, crosstalk values for PLCC packages are approximately 5 dB better.

AC Electrical Characteristics[†] - Control and I/O Timings- Voltages are with respect to $V_{DD}=5V$, $V_{SS}=0V$, $V_{EE}=-7V$, unless otherwise stated.

	Characteristics	Sym.	Min.	Typ. [‡]	Max.	Units	Test Conditions
1	Control Input crosstalk to switch (for CS, DATA, STROBE, Address)	CX_{talk}		30		mVpp	$V_{IN} = 3 V$ squarewave; $R_{IN} = 1 k\Omega$, $R_L = 10 k\Omega$. See Appendix, Fig. A.6
2	Digital Input Capacitance	C_{DI}		10		pF	$f = 1 MHz$
3	Switching Frequency	F_O			20	MHz	
4	Setup Time DATA to STROBE	t_{DS}	10			ns	$R_L = 1 k\Omega$, $C_L = 50 pF$ $\overset{\text{A}}{\text{A}}$
5	Hold Time DATA to STROBE	t_{DH}	10			ns	$R_L = 1 k\Omega$, $C_L = 50 pF$ $\overset{\text{A}}{\text{A}}$
6	Setup Time Address to STROBE	t_{AS}	10			ns	$R_L = 1 k\Omega$, $C_L = 50 pF$ $\overset{\text{A}}{\text{A}}$
7	Hold Time Address to STROBE	t_{AH}	10			ns	$R_L = 1 k\Omega$, $C_L = 50 pF$ $\overset{\text{A}}{\text{A}}$
8	STROBE Pulse Width	t_{SPW}	20			ns	$R_L = 1 k\Omega$, $C_L = 50 pF$ $\overset{\text{A}}{\text{A}}$
9	RESET Pulse Width	t_{RPW}	40			ns	$R_L = 1 k\Omega$, $C_L = 50 pF$ $\overset{\text{A}}{\text{A}}$
10	STROBE to Switch Status Delay	t_S		40	100	ns	$R_L = 1 k\Omega$, $C_L = 50 pF$ $\overset{\text{A}}{\text{A}}$
11	DATA to Switch Status Delay	t_D		50	100	ns	$R_L = 1 k\Omega$, $C_L = 50 pF$ $\overset{\text{A}}{\text{A}}$
12	RESET to Switch Status Delay	t_R		35	100	ns	$R_L = 1 k\Omega$, $C_L = 50 pF$ $\overset{\text{A}}{\text{A}}$

[†] Timing is over recommended temperature range. See Fig. 3 for control and I/O timing details.

Digital Input rise time (t_r) and fall time (t_f) = 5 ns.

[‡] Typical figures are at 25°C and are for design aid only; not guaranteed and not subject to production testing.

^A Refer to Appendix, Fig. A.7 for test circuit.

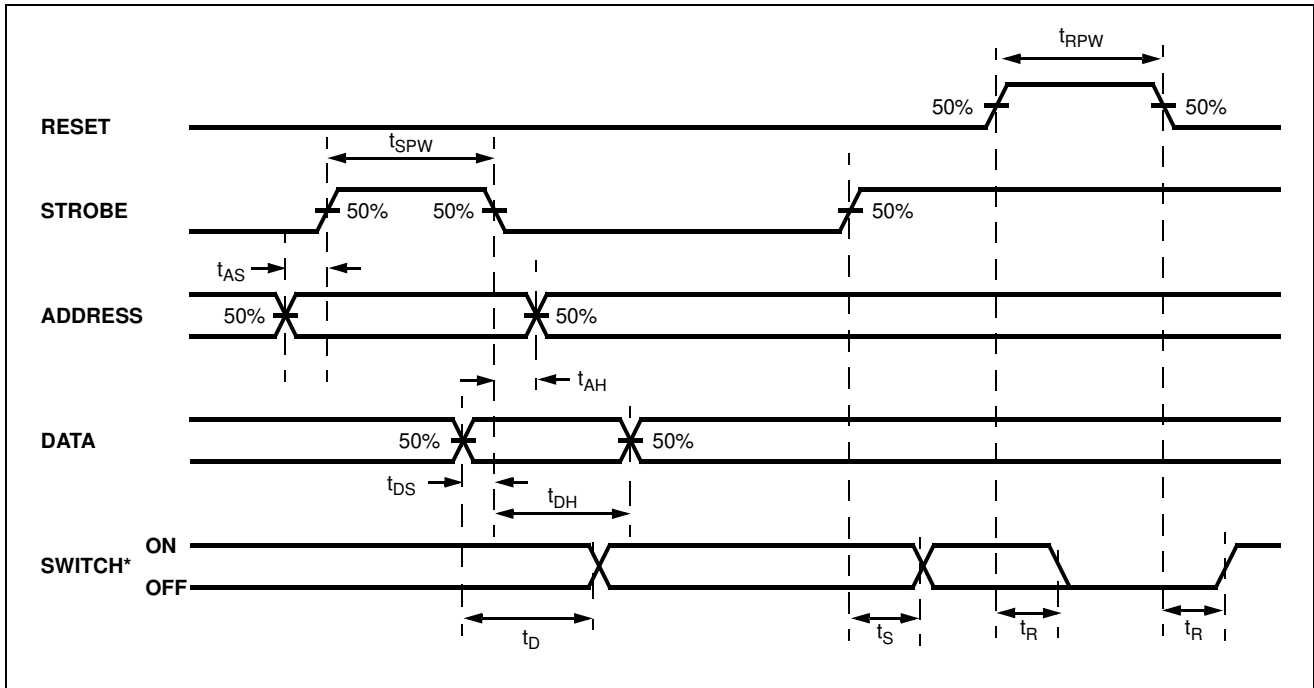
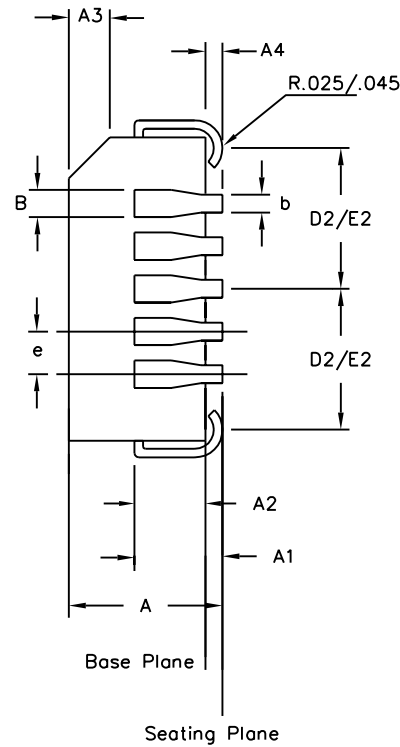
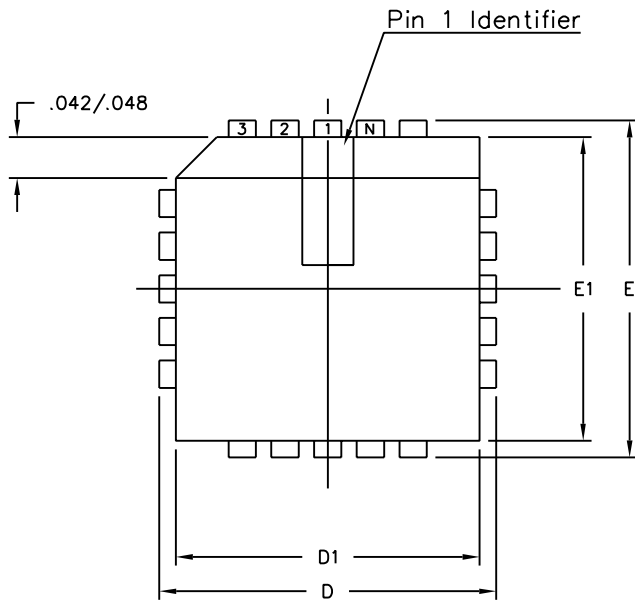


Figure 3 - Control Memory Timing Diagram

* See Appendix, Fig. A.7 for switching waveform

AY2	AY1	AY0	AX2	AX1	AX0	Connection	AY2	AY1	AY0	AX2	AX1	AX0	Connection
0	0	0	0	0	0	X0 Y0	1	0	0	0	0	0	X0 Y4
0	0	0	0	0	1	X1 Y0	1	0	0	0	0	1	X1 Y4
0	0	0	0	1	0	X2 Y0	1	0	0	0	1	0	X2 Y4
0	0	0	0	1	1	X3 Y0	1	0	0	0	1	1	X3 Y4
0	0	0	1	0	0	X4 Y0	1	0	0	1	0	0	X4 Y4
0	0	0	1	0	1	X5 Y0	1	0	0	1	0	1	X5 Y4
0	0	0	1	1	0	X6 Y0	1	0	0	1	1	0	X6 Y4
0	0	0	1	1	1	X7 Y0	1	0	0	1	1	1	X7 Y4
0	0	1	0	0	0	X0 Y1	1	0	1	0	0	0	X0 Y5
0	0	1	0	0	1	X1 Y1	1	0	1	0	0	1	X1 Y5
0	0	1	0	1	0	X2 Y1	1	0	1	0	1	0	X2 Y5
0	0	1	0	1	1	X3 Y1	1	0	1	0	1	1	X3 Y5
0	0	1	1	0	0	X4 Y1	1	0	1	1	0	0	X4 Y5
0	0	1	1	0	1	X5 Y1	1	0	1	1	0	1	X5 Y5
0	0	1	1	1	0	X6 Y1	1	0	1	1	1	0	X6 Y5
0	0	1	1	1	1	X7 Y1	1	0	1	1	1	1	X7 Y5
0	1	0	0	0	0	X0 Y2	1	1	0	0	0	0	X0 Y6
0	1	0	0	0	1	X1 Y2	1	1	0	0	0	1	X1 Y6
0	1	0	0	1	0	X2 Y2	1	1	0	0	1	0	X2 Y6
0	1	0	0	1	1	X3 Y2	1	1	0	0	1	1	X3 Y6
0	1	0	1	0	0	X4 Y2	1	1	0	1	0	0	X4 Y6
0	1	0	1	0	1	X5 Y2	1	1	0	1	0	1	X5 Y6
0	1	0	1	1	0	X6 Y2	1	1	0	1	1	0	X6 Y6
0	1	0	1	1	1	X7 Y2	1	1	0	1	1	1	X7 Y6
0	1	1	0	0	0	X0 Y3	1	1	1	0	0	0	X0 Y7
0	1	1	0	0	1	X1 Y3	1	1	1	0	0	1	X1 Y7
0	1	1	0	1	0	X2 Y3	1	1	1	0	1	0	X2 Y7
0	1	1	0	1	1	X3 Y3	1	1	1	0	1	1	X3 Y7
0	1	1	1	0	0	X4 Y3	1	1	1	1	0	0	X4 Y7
0	1	1	1	0	1	X5 Y3	1	1	1	1	0	1	X5 Y7
0	1	1	1	1	0	X6 Y3	1	1	1	1	1	0	X6 Y7
0	1	1	1	1	1	X7 Y3	1	1	1	1	1	1	X7 Y7

Table 1 - Address Decode Truth Table



Symbol	Control Dimensions in inches		Altern. Dimensions in millimetres	
	MIN	MAX	MIN	MAX
A	0.165	0.180	4.19	4.57
A1	0.090	0.120	2.29	3.05
A2	0.062	0.083	1.57	2.11
A3	0.042	0.056	1.07	1.42
A4	0.020	—	0.51	—
D	0.485	0.495	12.32	12.57
D1	0.450	0.456	11.43	11.58
D2	0.191	0.219	4.85	5.56
E	0.485	0.495	12.32	12.57
E1	0.450	0.456	11.43	11.58
E2	0.191	0.219	4.85	5.56
B	0.026	0.032	0.66	0.81
b	0.013	0.021	0.33	0.53
e	0.050	BSC	1.27	BSC
Pin features				
ND	7			
NE	7			
N	28			
Note	Square			
Conforms to JEDEC MS-018AB Iss. A				

Notes:

1. All dimensions and tolerances conform to ANSI Y14.5M-1982
2. Dimensions D1 and E1 do not include mould protrusions.
Allowable mould protrusion is 0.010" per side. Dimensions D1 and E1 include mould protrusion mismatch and are determined at the parting line, that is D1 and E1 are measured at the extreme material condition at the upper or lower parting line.
3. Controlling dimensions in Inches.
4. "N" is the number of terminals.
5. Not To Scale
6. Dimension R required for 120° minimum bend.

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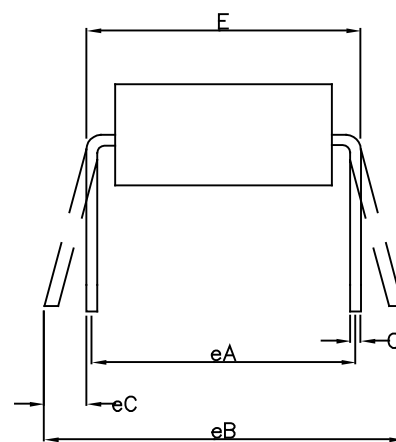
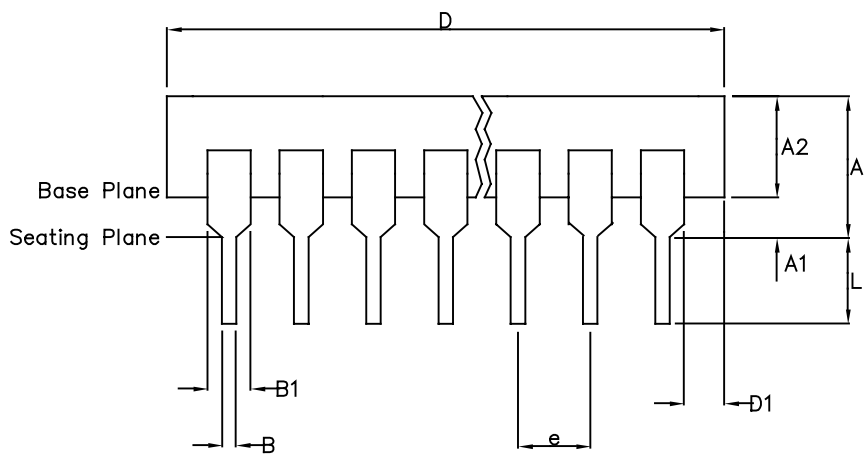
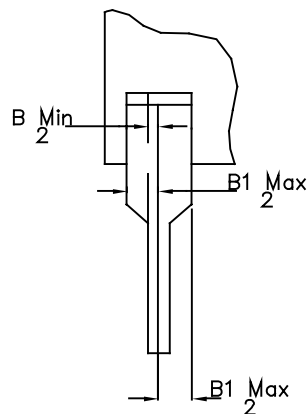
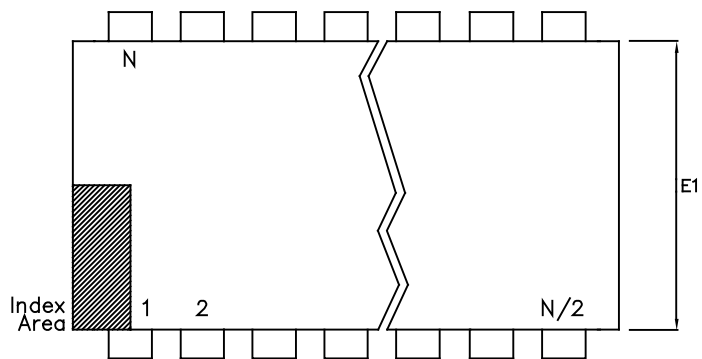
Previous package codes

HP / P

Package Code QA

Package Outline for
28 lead PLCC

GPD00002



	Min mm	Max mm	Min Inches	Max Inches
A		6.35		0.250
A1	0.38		0.015	
A2	3.18	4.95	0.125	0.195
B	0.36	0.56	0.014	0.022
B1	0.76	1.78	0.030	0.070
C	0.20	0.38	0.008	0.015
D	35.05	39.75	1.380	1.565
D1	0.13		0.005	
E	15.24	15.88	0.600	0.625
E1	12.32	14.73	0.485	0.580
e	2.54 BSC		0.100 BSC	
eA	15.24 BSC		0.600 BSC	
eB		17.78		0.700
L	2.92	5.08	0.115	0.200
N	28		28	
Conforms to Jeduc MS-011AB ISS.B				

- Notes:
1. Controlling Dimensions are in inches
 2. Dimension A, A1 and L are measured with the package seated in the Seating Plane
 3. Dimensions D & E1 do not include mould flash or protrusions. Mould flash or protrusion shall not exceed 0.010 inch.
 4. Dimensions E & eA are measured with leads constrained to be perpendicular to plane T.
 5. Dimensions eB & eC are measured at the lead tips with the leads unconstrained; eC must be zero or greater.

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ACN	7010	203532	213102	CDCA
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APPRD.				



Package Code	DA
Previous package codes	DP / E
	Package Outline for 28 lead 600mils PDIP
	GPD00072



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